

# EMB-LN8T

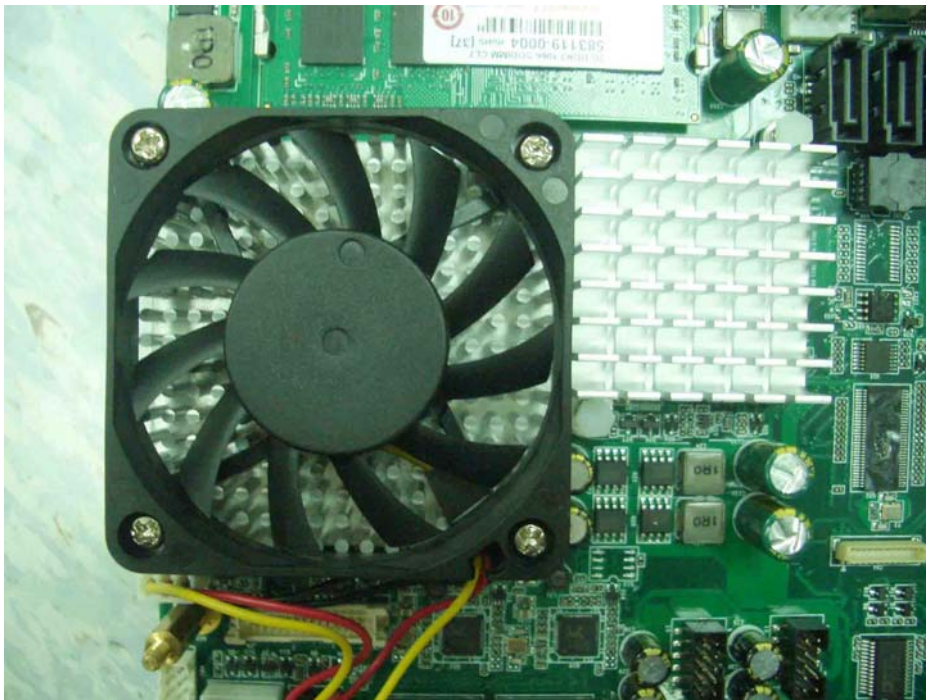
## Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> <b>Pass</b>			
	<input type="checkbox"/> <b>Fail</b>			
	<input type="checkbox"/> <b>Pass with Deviation</b>			
	<b>Comment:</b> _____			
<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date	Approval	Test Engineer
2011 / 08 / 10	Jansin Lee	Rex Chang

## Sample Configuration & Quantity Under Test

- Model name : EMB-LN8T A0.3\_0\_0
- CPU Board : EMB-LN8T A0.3\_0\_0
- CPU : Intel Atom D525 / 1.8GHz
- Memory : Transcend 2GB \* 2 / Hynix H5TQ2G830A H9C 105A
- 3.5" SATA HDD : Toshiba HDD 160GB / MK1165GSX
- BIOS : ELN-8T 0.10
- Test Software : Windows XP sp3 / Run Prime95 v26.5
- Power : AT Power to ATX Mode
- Cooler:

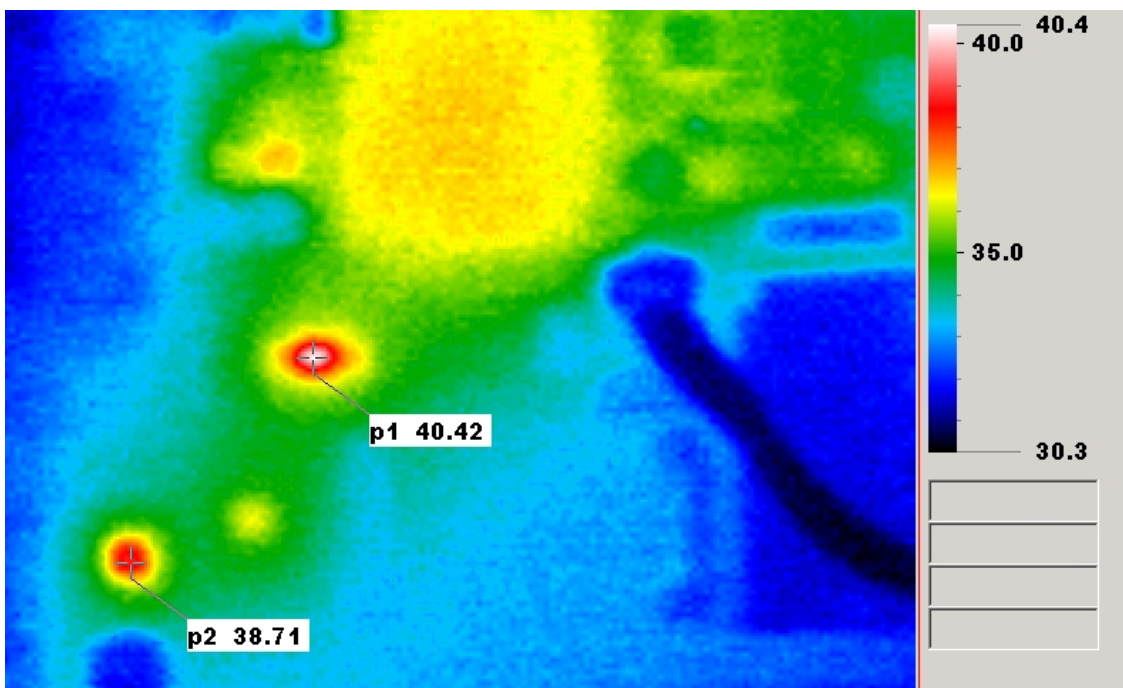
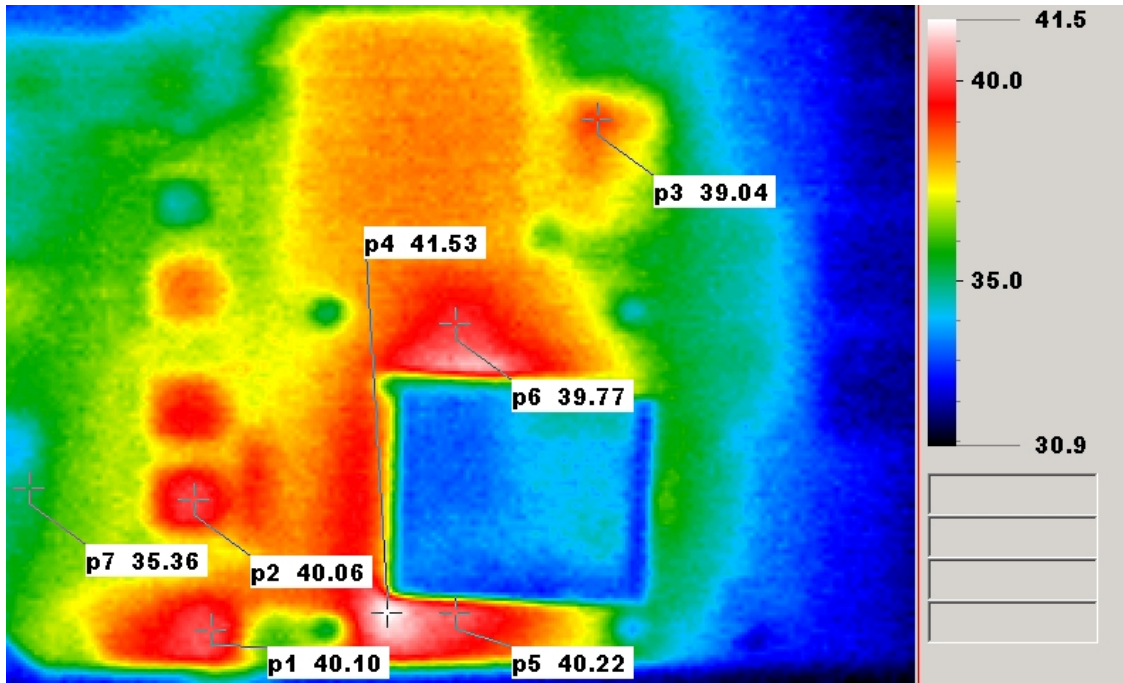


## Thermal Image Analysis

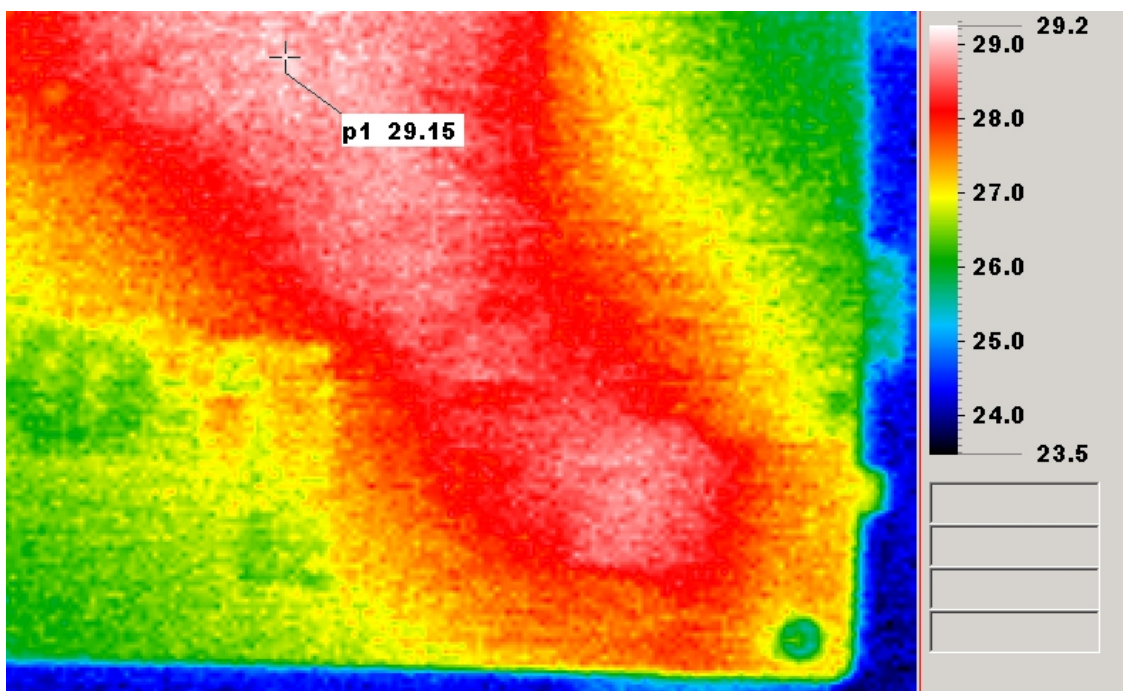
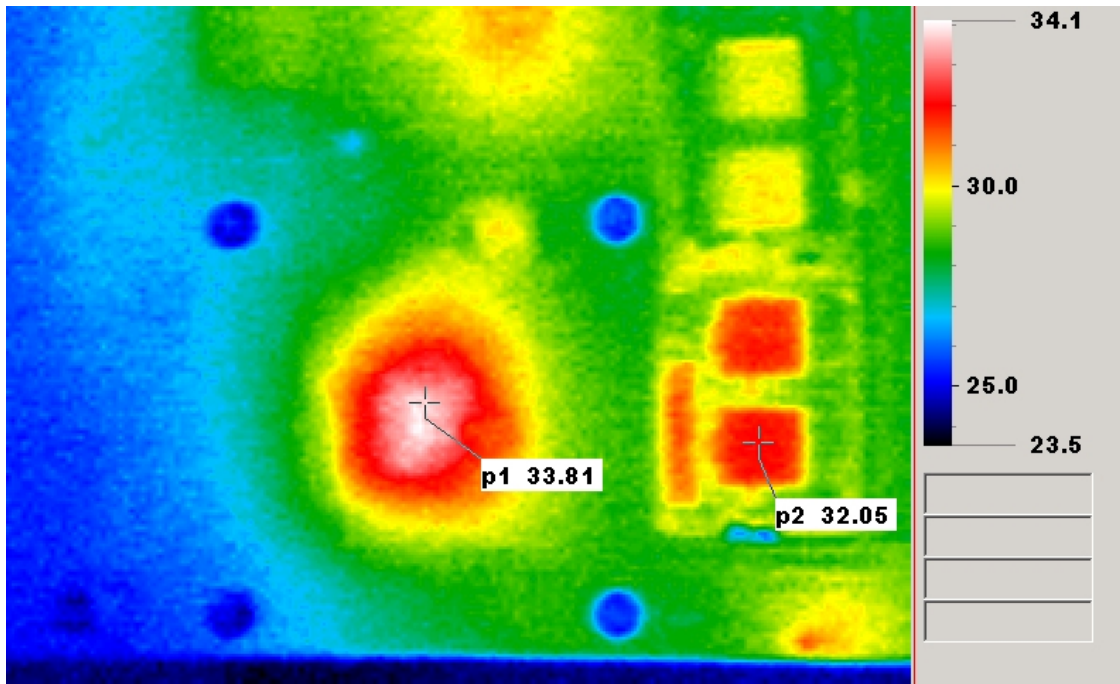
1. Test Date: 2011-08-09
2. Test Product: EMB-LN8T A0.3\_0\_0
3. Test Site: AAEON Internal Lab.
4. Temperature Measurement:
  1. 40 Channel Thermal Recorder:  
YOKOGAWA Inc,  
Model: DA100-13-1D  
Date of Calibration: 2010/11/08  
Serial Number: 12A323190
  2. IR Scanner: Infrared Camera  
NIPPON AVIONICS CO., LTD.  
Model: TVS-100  
Date of Calibration: 2011/07/11  
Serial Number: 0179L2746
5. Test Condition:  
Test by DA-100: 26.3°C with cooler
6. Take Picture Time:  
After power on 2 hours

### Temperature Profile Test:

Component Side:

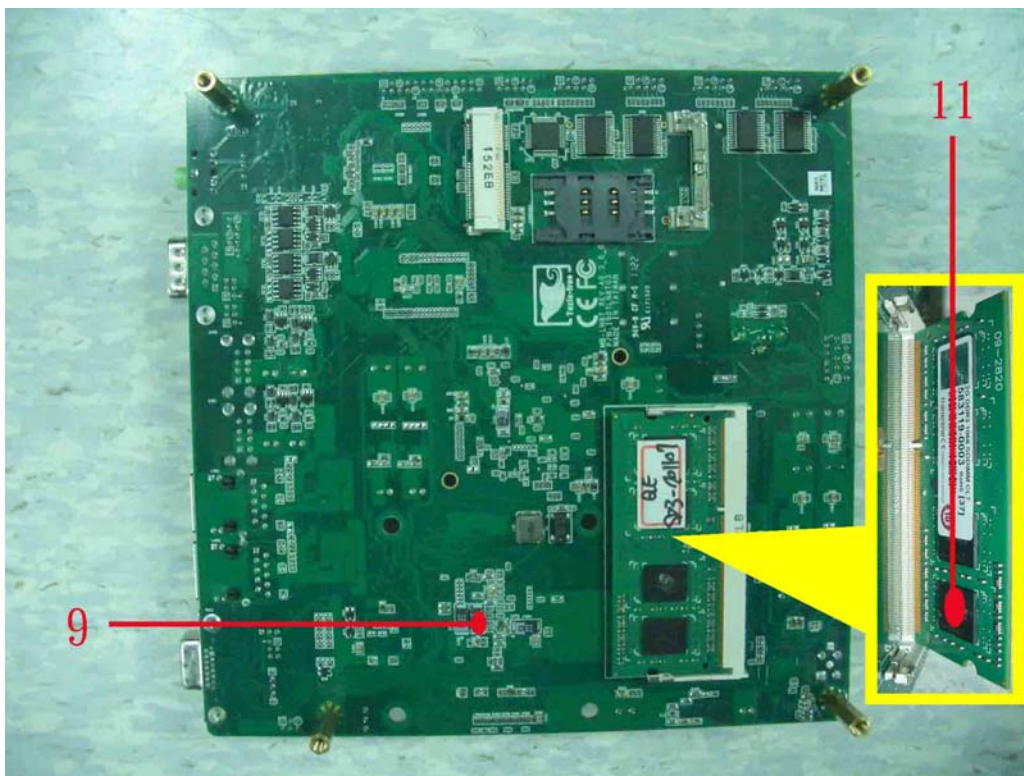
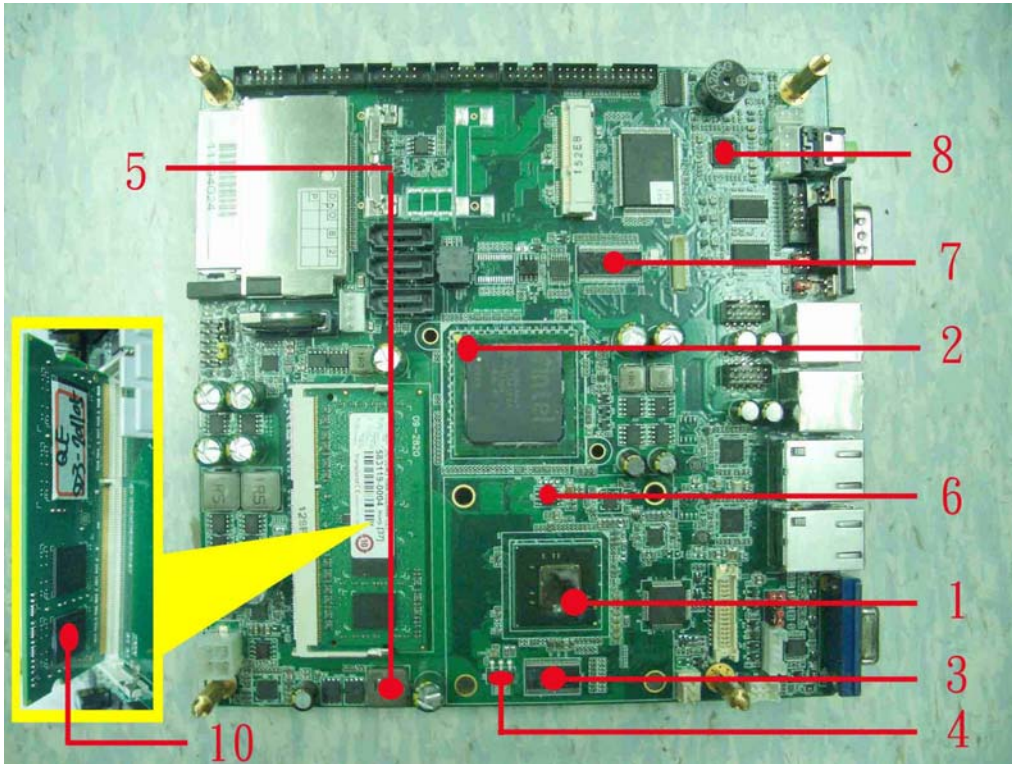


**Back Side:**



**Terminal Recorder:**

Measuring Thermal Couple Position :



**Using YOKOGAWA / DARWIN DA100-100-13-1D test**

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				26.3°C	60°C	
1	U26	(TF)Intel Atom D525 CPU	100	38.1	71.8	
2	U29	(TF)Chipset ICH8M.INTEL.NH82801HBM.SLB9A	105	33.4	67.1	
3	U27	(TF)LVDS.Receiver.exploretech.EP102	100	40.3	74.0	
4	Q52	(TF)REG.1A Dorpout Regulator.Fiti.FR1117R3GTR	125	41.8	75.5	
5	L31	(TF)COIL.Zenithtek.ZPWM-1040M-1R0M	125	34.7	68.4	
6	Q27	(TF)Dual N-Channel.APEC.AP4226AGM	125	32.7	66.4	
7	U22	(TF)CLOCK GENERATOR.IDT.9LPRS501PGLF	95	43.5	77.2	
8	U12	(TF)7.1Channel HD Audio Codec.VIA.VT1708B	85	38.9	72.6	
9	C403	(TF)POSCAP.SANYO.2R5TPE330MCC2	105	52.2	85.9	
10	-	Memory chipset - 1	95	33.8	67.5	
11	-	Memory chipset - 2	95	40.7	74.4	

**Note(\*):**

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. **Judgment Criteria:**
  - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
  - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.